



APPENDIX D

**(VERSION OF CLAIMS AS AMENDED HEREIN
WITH MARKINGS TO SHOW CHANGES MADE)**

(Serial No. 09/942,183)



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VERSION OF CLAIMS WITH MARKINGS TO SHOW CHANGES MADE

3. (Amended) The routing element of claim 2, wherein said ~~contacts~~contact pads are located on opposite sides of said polymeric film from one another.

12. (Amended) The assembly of claim 11, wherein said at least one conductive trace at least partially establishes communication between asaid bond pad of said at least one semiconductor device and a corresponding terminal of said substrate.

16. (Amended) The assembly of claim 15, wherein at least one conductive trace ~~of said plurality of conductive traces~~ carried by said polymeric film at least partially establishes communication between a bond pad of one of said at least two semiconductor devices and a corresponding bond pad of another of said at least two semiconductor devices.

20. (Amended) The assembly of claim 10, wherein said ~~plurality of at least one~~ conductive ~~traces~~trace ~~of said polymeric film provide~~provides a more direct electrical route ~~between~~ than any conductive trace carried by said substrate.

21. (Amended) The assembly of claim 16, wherein another bond pad of said at least one semiconductor device is in communication with at least a terminal of said substrate by way of another conductive trace carried by said polymeric film.

29. (Amended) The carrier of claim 28, wherein communication between said at least one terminal and said another ~~terminal~~terminal is further established by way of at least one discrete conductive element that electrically connects said at least one additional conductive trace to at least one of said at least one terminal and said another terminal.

69. (Amended) The assembly of claim ~~58~~59, wherein said second plurality of conductive traces of said routing element provide a more direct electrical route ~~between~~ than any conductive trace carried by said substrate.

70. (Amended) The assembly of claim 65, wherein another bond pad of said at least one semiconductor device is in communication with at least a terminal of said substrate by way of another conductive trace of said second plurality of conductive traces.

71. (Amended) The assembly of claim 59, wherein said routing element and said ~~at least one~~second plurality of conductive trace extends traces extends through a plane of said substrate.

72. (Amended) The assembly of claim 71, wherein opposite ends of ~~said~~ at least one conductive trace of said second plurality of conductive traces are electrically exposed at opposite sides of said routing element.

73. (Amended) The assembly of claim 71, wherein opposite ends of ~~said~~ at least one conductive trace of said second plurality of conductive traces are electrically exposed at the same side of said routing element.